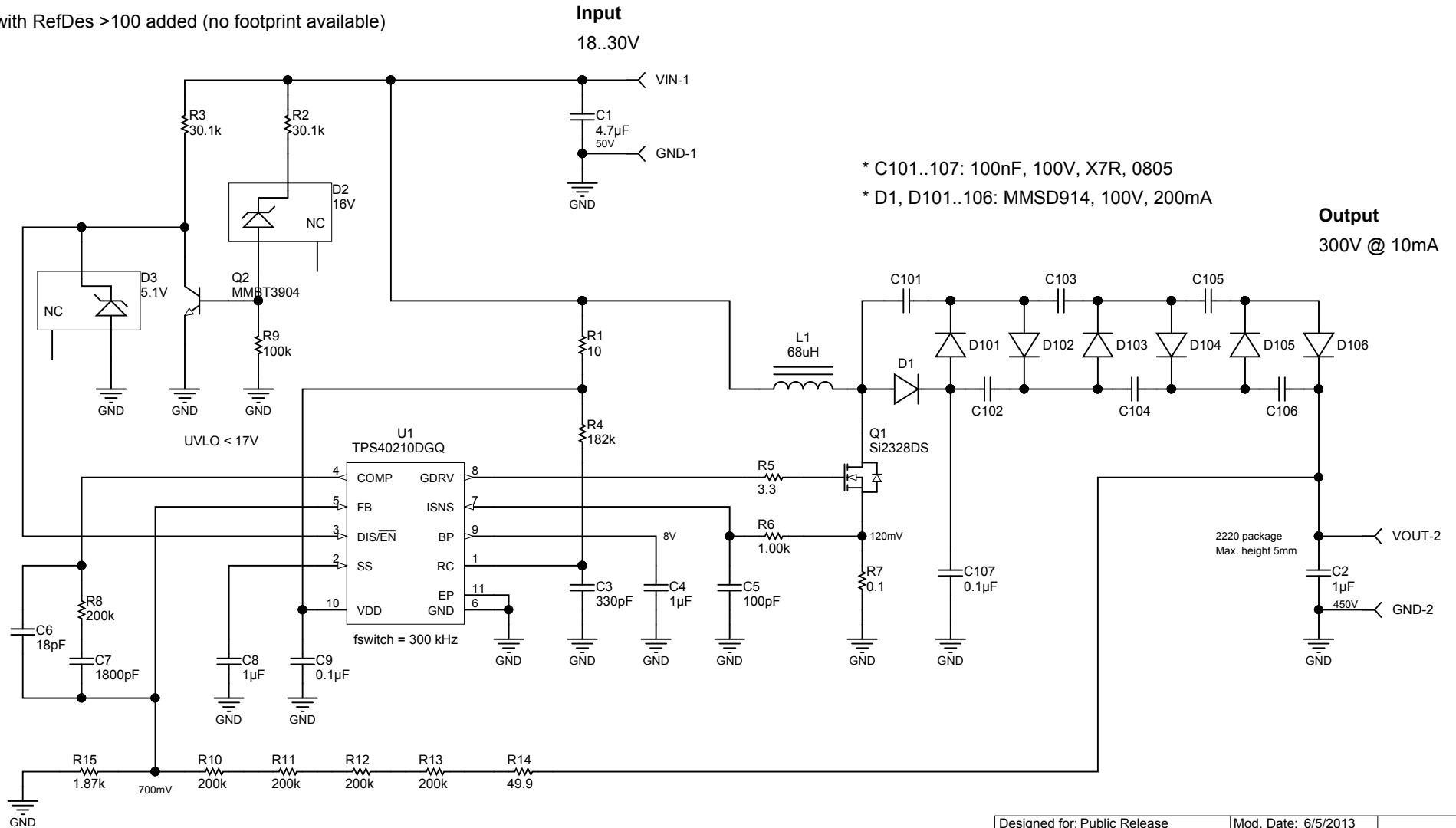


Design Notes

- * Converter is working in discontinuous conduction mode
- * Duty cycle is 30..62%
- * R14 is necessary only for test purpose
- * Built on PCB PMP8621 Rev.B
- * Parts with RefDes >100 added (no footprint available)

Revision History	
Revision	Notes
A	* Paper Design
B	* Layout of PCB
C	* Built & tested, added cascade



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Number: PMP8621 Rev: C
SVN Rev: Not in version control
Drawn By:
Engineer: Matthias Ulmann

Designed for: Public Release Mod. Date: 6/5/2013
Project Title: 18..30V -> 300V @ 10mA
Sheet Title:
Assembly Variant: Variant name not interpreted Sheet: 1 of 1
File: PMP8621RevC.SchDoc Size: A4
Contact: http://www.ti.com/support



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